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	Application No.	Applicant(s)
A	10/811,370	HU ET AL.
Notice of Allowability	Examiner	Art Unit
	Tu-Tu Ho	2818
The MAILING DATE of this communication apperature All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIOF of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this app or other appropriate communication GHTS. This application is subject to	olication. If not included will be mailed in due course. THIS
1. \boxtimes This communication is responsive to <u>Amendment filed 10/3</u>	<u>24/2005</u> .	
2. The allowed claim(s) is/are <u>15,17-27,29 and 30</u> .		
3. ☐ Acknowledgment is made of a claim for foreign priority una) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents have 2. ☐ Certified copies of the priority documents have 3. ☐ Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 4. ☐ A SUBSTITUTE OATH OR DECLARATION must be submin INFORMAL PATENT APPLICATION (PTO-152) which give 5. ☐ CORRECTED DRAWINGS (as "replacement sheets") must (a) ☐ including changes required by the Notice of Draftspers 1) ☐ hereto or 2) ☐ to Paper No./Mail Date (b) ☐ including changes required by the attached Examiner's	e been received. been received in Application No cuments have been received in this is of this communication to file a reply of this application. itted. Note the attached EXAMINER' ces reason(s) why the oath or declarates the submitted. son's Patent Drawing Review (PTO-1).	national stage application from the complying with the requirements S AMENDMENT or NOTICE OF tion is deficient.
Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1 each sheet. Replacement sheet(s) should be labeled as such in t		
6. DEPOSIT OF and/or INFORMATION about the depo attached Examiner's comment regarding REQUIREMENT		
Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SB/C Paper No./Mail Date 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. ☐ Interview Summary Paper No./Mail Dat 7. ☑ Examiner's Amenda 8. ☑ Examiner's Stateme	e .
	9.	Tu-Tu Ho Nov. 28, 2005

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DETAILED ACTION

1. Applicant's Amendment filed 10/24/2005 has been reviewed and placed of record in the file.

EXAMINER'S AMENDMENT

- 2. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.
- 3. This application is in condition for allowance except for the presence of claims 1-14 non-elected without traverse. Accordingly, claims 1-14 have been cancelled.
- 4. Claim 15, lines 7, "mounted to die carrier" has been changed to:

"mounted to the die carrier";

Claim 24, lines 6, "mounted to die carrier" has been changed to:

"mounted to the die carrier";

Claim 17, "claim 16" has been changed to:

"claim 15";

Claim 29, "claim 28" has been changed to:

"claim 24".

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Allowable Subject Matter

5. Claims 15, 17-27, and 29-30 (to be renumbered 1-14) are allowable over the prior art of

record.

The following is an examiner's statement of reasons for allowance: The prior art of record

fails to teach or render obvious a system including a bumpless die with all limitations as recited

in claims 15 and 24, comprising the bumpless die having a planar surface with a plurality of

embedded bonding pads, a heat spreader lid having the bumpless die mounted in a compliance

manner with the heat spreader lid to form a module, a die carrier having a plurality of solder

bumps attached thereto, the module mounted to the die carrier with the solder bumps being

bonded to the embedded bonding pads when the module is mounted to the die carrier, the die

having a thickness no greater than 50 microns, and a bonding hard-solder thermal interface

interposed between the die and the heat spreader lid to bond the die to the heat spreader lid.

Any comments considered necessary by applicant must be submitted no later than the

payment of the issue fee and, to avoid processing delays, should preferably accompany the issue

fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for

Allowance."

Conclusion

6. The prior art made of record and not relied upon is considered pertinent to applicant's

disclosure.

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Hua et al. U.S. Patent Application Publication 20040188817 disclose a semiconductor chip having a copper layer deposited to the back surface of the semiconductor chip, the chip is ultra-thin and having a thickness accommodating that of the copper layer to minimize chip warpage.

7. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tu-Tu Ho whose telephone number is (571) 272-1778. The examiner can normally be reached on 6:30 am - 5:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, DAVID NELMS can be reached on (571) 272-1787. The fax phone number for the organization where this application or proceeding is assigned is (571) 273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tu-Tu Ho

November 28, 2005